

Title (en)
LIGHT EMITTING DEVICE

Title (de)
LICHTEMITTIERENDE VORRICHTUNG

Title (fr)
DISPOSITIF ÉMETTEUR DE LUMIÈRE

Publication
EP 2485284 A4 20141203 (EN)

Application
EP 10820487 A 20100927

Priority
• JP 2009229187 A 20091001
• JP 2010066701 W 20100927

Abstract (en)
[origin: EP2485284A1] [Object] Disclosed is a light emitting device that enables a small and lightweight semiconductor package to be precisely mounted on a packaging substrate. [Means for Solving Problem] A light emitting device being such that a semiconductor package equipped with a first conduction member and a second conduction member, and a mounting board equipped with a first wiring component and a second wiring component that are respectively connected to the first conduction member and the second conduction member by a joining member, the semiconductor package comprises: a light emitting element; a first conduction member, on one side of which the light emitting element is placed; and a second conduction member whose surface area is smaller than that of the first conduction member, the other side of the first conduction member and the second conduction member, on the opposite side from said one side, forms the lower face of the semiconductor package, and the mounting board comprises: a narrow part and a wide part that extends away from the first and second conduction members and is wider than the narrow part, which are formed on the first wiring component and the second wiring component, at least the narrow part is joined to the first conduction member and the second conduction member, and the first wiring component has a recess in its interior.

IPC 8 full level
H01L 33/48 (2010.01)

CPC (source: EP US)
H01L 33/486 (2013.01 - EP US); **H01L 33/62** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/48257** (2013.01 - EP US); **H01L 2224/48465** (2013.01 - EP US); **H01L 2924/01322** (2013.01 - EP US); **H01L 2924/12044** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)
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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)
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EP 10820487 A 20100927; CN 201080044079 A 20100927; JP 2010066701 W 20100927; JP 2011534232 A 20100927; JP 2015091744 A 20150428; TW 99133583 A 20101001; US 201013498493 A 20100927